Modeling and Mitigating Early Retention Loss and Process Variation in 3D Flash

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#### NAND Flash Memory Lifetime Problem



#### Planar vs. 3D NAND Flash Memory





Planar NAND Flash Memory **3D NAND** Flash Memory

Reduce flash cell size, Reduce distance b/w cells

Increase # of layers

**Reliability** Scaling hurts reliability

**Scaling** 

Not well studied!

### **Executive Summary**

- Problem: 3D NAND error characteristics are **not well studied**
- Goal: Understand & mitigate 3D NAND errors to improve lifetime
- Contribution 1: Characterize real 3D NAND flash chips
  - **Process variation: 21**× error rate difference across layers
  - Early retention loss: Error rate increases by 10× after 3 hours
  - **Retention interference: Not observed before** in planar NAND
- Contribution 2: Model RBER and threshold voltage
  - RBER (raw bit error rate) variation model
  - Retention loss model
- Contribution 3: Mitigate 3D NAND flash errors
  - LaVAR: Layer Variation Aware Reading
  - LI-RAID: Layer-Interleaved RAID
  - ReMAR: Retention Model Aware Reading
  - Improve flash lifetime by **1.85**× or reduce ECC overhead by **78.9%**

# Agenda

- Background & Introduction
- Contribution 1: Characterize real 3D NAND flash chips
- Contribution 2: Model RBER and threshold voltage
- Contribution 3: Mitigate 3D NAND flash errors
- Conclusion

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#### **Process Variation Across Layers**



#### **Characterization Methodology**

- Modified firmware version in the flash controller
  - Controls the read reference voltage of the flash chip
  - Bypasses ECC to get raw data (with raw bit errors)
- Analysis and post-processing of the data on the server



#### Layer-to-Layer Process Variation



#### Layer-to-Layer Process Variation



#### Large RBER variation across layers and LSB-MSB pages

#### **Retention Loss Phenomenon**

**Planar NAND Cell** 

**3D NAND Cell** 



#### Most dominant type of error in planar NAND. Is this true for 3D NAND as well?

### **Early Retention Loss**



**Retention errors increase quickly immediately after programming** 

### **Characterization Summary**

- Layer-to-layer process variation
  - Large RBER variation across layers and LSB-MSB pages
  - $\rightarrow$  Need new mechanisms to tolerate RBER variation!
- Early retention loss
  - RBER increases quickly after programming
  - $\rightarrow$  Need new mechanisms to tolerate retention errors!
- Retention interference
  - Amount of retention loss correlated with neighbor cells' states
  - $\rightarrow$  Need new mechanisms to tolerate retention interference!
- More threshold voltage and RBER results in the paper: 3D NAND P/E cycling, program interference, read disturb, read variation, bitline-to-bitline process variation
- **Our approach** based on insights developed via our experimental characterization: Develop **error models**, and build online **error mitigation mechanisms** using the models



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#### What Do We Model?



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#### **Optimal Read Reference Voltage**



#### **Retention Loss Model**



## **Retention Loss Model**

- Goal: Develop a simple linear model that can be used online
- Models
  - Optimal read reference voltage ( $V_b$  and  $V_c$ )
  - Raw bit error rate (*log*(*RBER*))
  - Mean and standard deviation of threshold voltage distribution ( $\mu$  and  $\sigma$ )
- As a function of
  - Retention time (log(t))
  - P/E cycle count (**PEC**)
- e.g.,  $V_{opt} = (\alpha \times PEC + \beta) \times log(t) + \gamma \times PEC + \delta$
- Model error <1 step for *V<sub>b</sub>* and *V<sub>c</sub>*
- Adjusted  $R^2 > 89\%$

## **RBER Variation Model**



#### Variation-agnostic V<sub>opt</sub>

• Same V<sub>ref</sub> for all layers optimized for the entire block

**RBER distribution follows gamma distribution** 

**KL-divergence error = 0.09** 

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#### LaVAR: Layer Variation Aware Reading

- Layer-to-layer process variation
  - Error characteristics are different in each layer
- Goal: Adjust read reference voltage for each layer
- Key Idea: Learn a voltage offset (Offset) for each layer •  $V_{opt}^{Layer aware} = V_{opt}^{Layer agnostic} + Offset$
- Mechanism
  - Offset: Learned once for each chip & stored in a table
    - Uses (2 × Layers) Bytes memory per chip
  - $V_{opt}^{Layer agnostic}$ : Predicted by any existing  $V_{opt}$  model
    - E.g., ReMAR [Luo+Sigmetrics'18], HeatWatch [Luo+HPCA'18], OFCM [Luo+JSAC'16], ARVT [Papandreou+GLSVLSI'14]

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• Reduces RBER on average by **43%** (based on our characterization data)

### LI-RAID: Layer-Interleaved RAID

- Layer-to-layer process variation
  - Worst-case RBER much higher than average RBER
- Goal: Significantly reduce worst-case RBER
- Key Idea
  - Group flash pages on *less reliable layers* with pages on *more reliable layers*
  - Group *MSB pages* with *LSB pages*
- Mechanism
  - Reorganize RAID layout to eliminate worst-case RBER
  - <0.4% storage overhead</li>

## **Conventional RAID**

Wordline #	Layer #	Page	Chip 0	Chip 1	Chip 2	Chip 3
0	0	MSB	Group 0	Group 0	Group 0	Group 0
0	0	LSB	Group 1	Group 1	Group 1	Group 1
1	1	MSB	Group 2	Group 2	Group 2	Group 2
1	1	LSB	Group 3	Group 3	Group 3	Group 3
2	2	MSB	Group 4	Group 4	Group 4	Group 4
2	2	LSB	Group 5	Group 5	Group 5	Group 5
3	3	MSB	Group 6	Group 6	Group 6	Group 6
3	3	LSB	Group 7	Group 7	Group 7	Group 7

Worst-case RBER in any layer limits the lifetime of conventional RAID

#### LI-RAID: Layer-Interleaved RAID

Wordline #	Layer #	Page	Chip 0	Chip 1	Chip 2	Chip 3
0	0	MSB	Group 0	Blank	Group 4	Group 3
0	0	LSB	Group 1	Blank	Group 5	Group 2
1	1	MSB	Group 2	Group 1	Blank	Group 5
1	1	LSB	Group 3	Group 0	Blank	Group 4
2	2	MSB	Group 4	Group 3	Group 0	Blank
2	2	LSB	Group 5	Group 2	Group 1	Blank
3	3	MSB	Blank	Group 5	Group 2	Group 1
3	3	LSB	Blank	Group 4	Group 3	Group 0

Any page with worst-case RBER can be corrected by other reliable pages in the RAID group

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  - Group *MSB pages* with *LSB pages*
- Mechanism
  - Reorganize RAID layout to eliminate worst-case RBER
  - <0.8% storage overhead</p>
- Reduces worst-case RBER by 66.9% (based on our characterization data)



### **ReMAR: Retention Model Aware Reading**

#### • Early retention loss

- Threshold voltage shifts quickly after programming
- Goal: Adjust read reference voltages based on retention loss
- Key Idea: Learn and use a retention loss model online

#### Mechanism

- Periodically characterize and learn retention loss model online
- Retention time = Read timestamp Write timestamp
  - Uses **800 KB** memory to store program time of each block
- Predict retention-aware  $V_{opt}$  using the model
- Reduces RBER on average by **51.9%** (based on our characterization data)

### Impact on System Reliability



LaVAR, LI-RAID, and ReMAR improve flash lifetime or reduce ECC overhead significantly

### **Error Mitigation Techniques Summary**

- LaVAR: Layer Variation Aware Reading
  - Learn a V<sub>opt</sub> offset for each layer and apply *layer-aware V<sub>opt</sub>*
- LI-RAID: Layer-Interleaved RAID
  - Group flash pages on *less reliable layers* with pages on *more reliable layers*
  - Group *MSB pages* with *LSB pages*
- ReMAR: Retention Model Aware Reading
  - Learn retention loss model and apply *retention-aware V<sub>opt</sub>*
- Benefits:
- Improve flash lifetime by **1.85**× or reduce ECC overhead by **78.9%**
- **ReNAC (in paper):** Reread a failed page using V<sub>opt</sub> based on the *retention interference* induced by neighbor cell

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Download our SIGMETRICS 2018 Paper at http://ece.cmu.edu/~saugatag/papers/ 18sigmetrics\_3dflash.pdf



# **References to Papers and Talks**



## **Our FMS Talks and Posters**

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## Our Flash Memory Works (II)

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- Arash Tavakkol, Juan Gomez-Luna, Mohammad Sadrosadati, Saugata Ghose, and Onur Mutlu, <u>MQSim: A Framework for Enabling Realistic</u> <u>Studies of Modern Multi-Queue SSD Devices</u>, FAST 2018.
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  - Yu Cai, Yixin Luo, Erich F. Haratsch, Ken Mai, and Onur Mutlu, <u>Data</u> <u>Retention in MLC NAND Flash Memory: Characterization</u>, <u>Optimization and Recovery</u>, HPCA 2015.
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## **Referenced Papers and Talks**

- All are available at
  - <u>https://safari.ethz.ch/publications/</u>
  - <u>https://www.ece.cmu.edu/~safari/talks.html</u>
- And, many other previous works on
  - Challenges and opportunities in memory
  - NAND flash memory errors and management
  - Phase change memory as DRAM replacement
  - STT-MRAM as DRAM replacement
  - Taking advantage of persistence in memory
  - Hybrid DRAM + NVM systems
  - NVM design and architecture

